

PATENT APPLICATION



Assistant Commissioner for Patents Box Patent Application Washington, D. C. 20231

Sir:

Enclosed herewith for filing is the following utility patent application:

Applicant(s):

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Lawrence Chung-Lai Lei

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Title of Application:

ATOMIC LAYER DEPOSITION APPARATUS

Pages of specification: 10 (including 3 pages of claims and

1 page of abstract)

Sheets of drawing: 4

Executed on:

Docket No.: 5017/ISM/CORE MCVD/SB

	PATENT APPLICATION FILING FEE CALCULATION				1	
	No. Filed	Less	Rate	e/Claim	Fe	е
Total Claims	11	-20	0	x \$18.00	\$	0.00
Independent Claims	3	- 3	0	x \$80.00	\$	0.00
	Minimum Filing Fee			\$710.00		
		ole Deper oplicable		cy Fee \$270.00)	\$	
	50% Reducti (Independen Corporatio Concern) -	t Invent n, or Sm	or, mall	Non-profit Business		

TOTAL FILING FEE

verified statement attached - \$ 0.00

\$710.00

Kindly charge the entire and/or any additional filing fee, as appropriate, to deposit account number 50-1074. To facilitate that charge, a duplicate copy of this letter is enclosed herewith.

Please direct all correspondence to: Patent Counsel Applied Materials, Inc. 3050 Bowers Avenue P.O. Box 450A Santa Clara, CA 95052

Also enclosed herewith for filing in connection with the enclosed application are:

ene	Oath; X Declaration and Power of Attorney; X Disclosure Statement; Letter referencing previously filed disclosure document; number filed; Verified Statement claiming small entity status; X An assignment of the application to Applied Materials, Inc.; Claim(s) to priority:
<u> </u>	Serial Number Filing date A certified copy of a patent application or inventor's certificate, filed and serial no, upon which a claim to priority is made; X 4 sheets of formal drawings.
14. Hall thin thin thin tall	Respectfully submitted, 7-27-01 Robert W. Mulcahy, Attorney Reg. No. 25,436
	EXPRESS MAIL CERTIFICATION "Express Mail" mailing label number: FL276123645US Date of deposit: 7-27-0/
	I hereby certify that this patent application and related papers is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to the Assistant Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.
	Signature of person mailing paper or fee Name of person mailing paper or fee

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